

客户 (Customer) : _____

承认书

Approval Sheet

谨致执事者：兹提供敝公司之有关详细规格及图面数据, 敬请给予办理试认定手续。
同时敬请送返一份附有贵公司签认之测试认定后之样品承认书。

We are pleased in sending you herewith on specification and drawings for your approval.
Please return to us one copy "Approval sheet" with your approved signature.

型号 (Model No.) : A-SL630Y3AC-F02-2T

发文日期 (Issue Date) : 2016/07/15 承认日期 (Approved Date) : _____

Checking signature of Amicc

Designer	Checker	Approver
Gordon		

Approval signature of customer

Designer	Checker	Approver

江苏欧密格光电科技股份有限公司

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Top view LED Type ■ PLCC Package

A-SL630Y3AC-F02-2T



Features

- PLCC-2 package
- Wide viewing angle
- Pb-free
- RoHS compliant
- Top view LED

Description

The Amicc 630 package has high efficacy, high power consumption, wide viewing angle and a compact form factor. These features make this package an ideal LED for all lighting applications.

Applications

- General lighting
- Decorative and Entertainment Lighting
- Indicators
- Illumination
- Switch lights

Device Selection Guide

Chip Materials	Emitted Color	Resin Color
AlGaInP	Yellow	Water Clear

Absolute Maximum Ratings ($T_{\text{Soldering}}=25^{\circ}\text{C}$)

Parameter	Symbol	Rating	Unit
Forward Current	I_F	70	mA
Peak Forward Current ($T=1.0\text{ms}$, $t_p=0.1\text{ms}$)	I_{FP}	200	mA
Power Dissipation	P_d	130	mW
Operating Temperature	T_{opr}	-40 ~ +85	$^{\circ}\text{C}$
Storage Temperature	T_{stg}	-40 ~ +100	$^{\circ}\text{C}$
Electrostatic Discharge(HBM)	ESD	2000	V
Soldering Temperature	T_{sol}	Reflow Soldering : 260 $^{\circ}\text{C}$ for 10 sec. Hand Soldering : 350 $^{\circ}\text{C}$ for 3 sec.	

Note:

The products are sensitive to static electricity and must be carefully taken when handling products.

Electro-Optical Characteristics ($T_{\text{Soldering}}=25^{\circ}\text{C}$)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I_v	1420	-----	2850	mcd	$I_F=40\text{mA}$
Peak Wavelength	λ_p	-----	591.0	-----	nm	$I_F=40\text{mA}$
Dominant Wavelength	λ_d	587.0	-----	593.0	nm	$I_F=40\text{mA}$
Forward Voltage	V_F	1.8	-----	2.4	V	$I_F=40\text{mA}$
Viewing Angle	$2\theta_{1/2}$	-----	120	-----	deg	$I_F=40\text{mA}$
Reverse Current	I_R	-----	-----	1	μA	$V_R=5\text{V}$

Notes:

1. Tolerance of Luminous Intensity $\pm 10\%$.
2. Tolerance of Dominant Wavelength: $\pm 1\text{nm}$.
3. Tolerance of Forward Voltage : $\pm 0.1\text{V}$.

Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
AW2	1420	1800	mcd	I _F =40mA
AX1	1800	2250		
AX2	2250	2850		

Note:
Tolerance of Luminous Intensity: ±10%.

Bin Range of Dominant Wavelength

Bin Code	Min.	Max.	Unit	Condition
YD1	587.0	589.0	nm	I _F =40mA
YD2	589.0	591.0		
YD3	591.0	593.0		

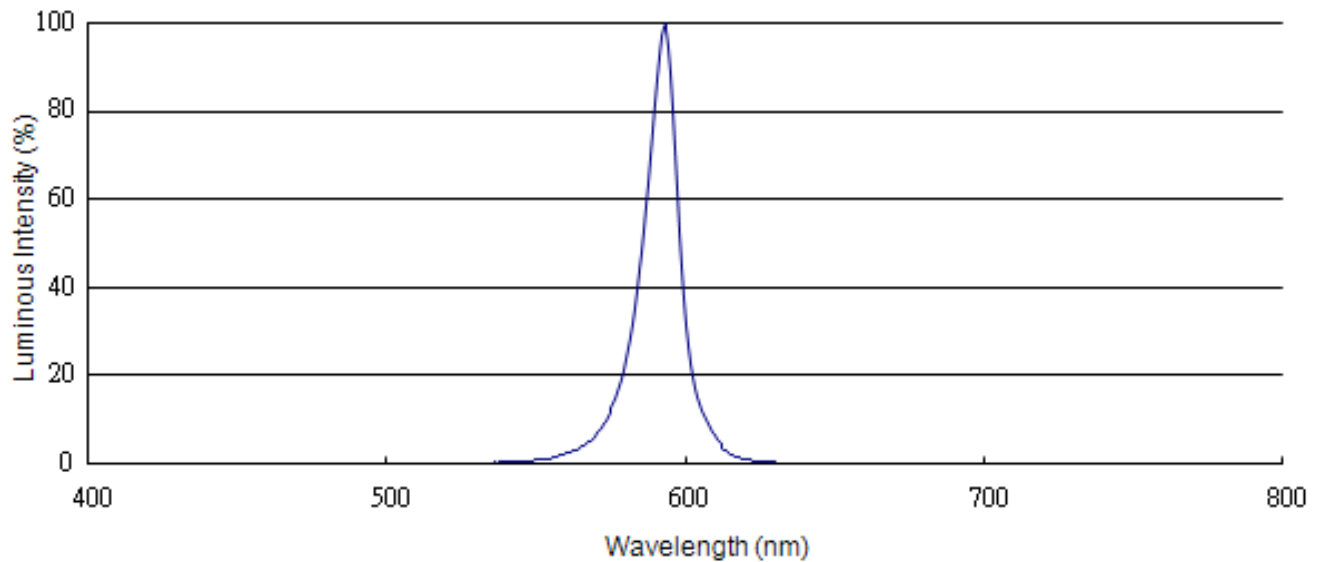
Note:
Tolerance of Dominant Wavelength: ±1nm.

Bin Range of Forward Voltage

Bin Code	Min.	Max.	Unit	Condition
25	1.80	1.90	V	I _F =40mA
26	1.90	2.00		
27	2.00	2.10		
28	2.10	2.20		
29	2.20	2.30		
30	2.30	2.40		

Note:
Tolerance of Forward Voltage: ±0.1V.

Spectrum Distribution



Typical Electro-Optical Characteristics Curves

Fig.1-Forward Voltage Shift vs. Junction Temperature

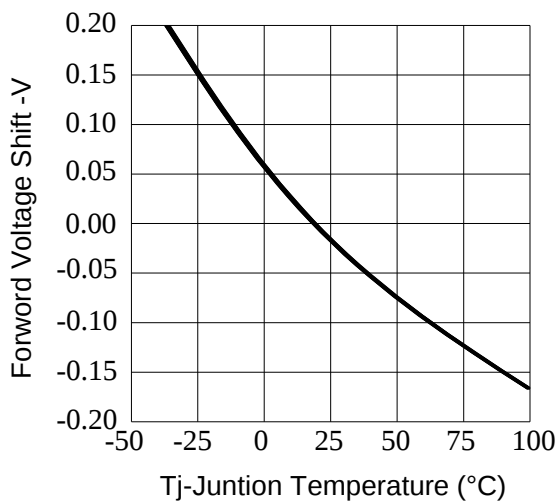
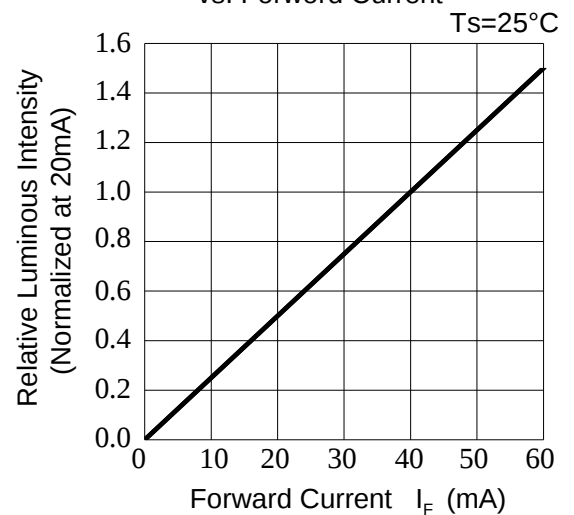


Fig.2-Relative Luminous Intensity vs. Forward Current



Typical Electro-Optical Characteristics Curves

Fig.3-Relative Luminous Intensity vs.Juntion Temperature

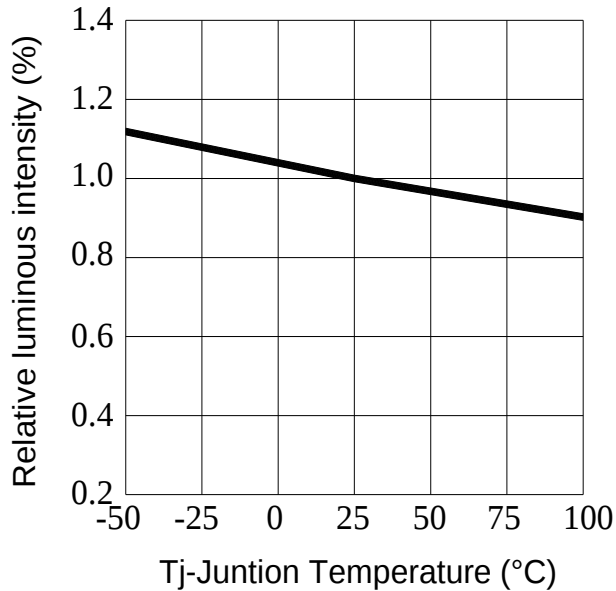


Fig.4-Forward Current vs. Forward Voltage $T_a=25^{\circ}\text{C}$

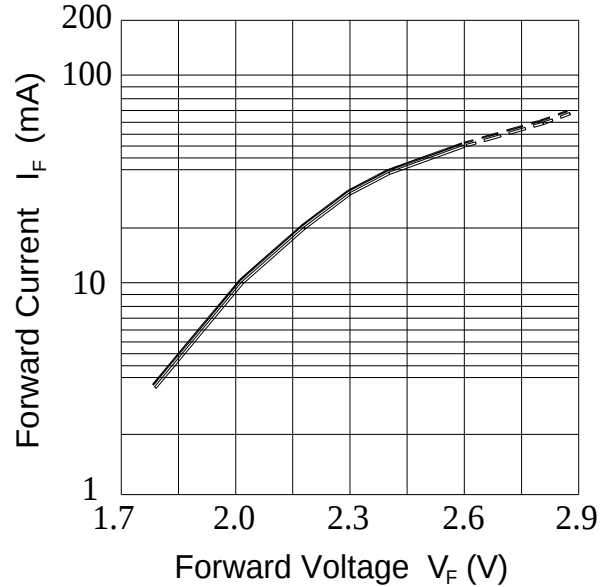


Fig.5-Max.Driving Forward Current vs.Soldering Temperture

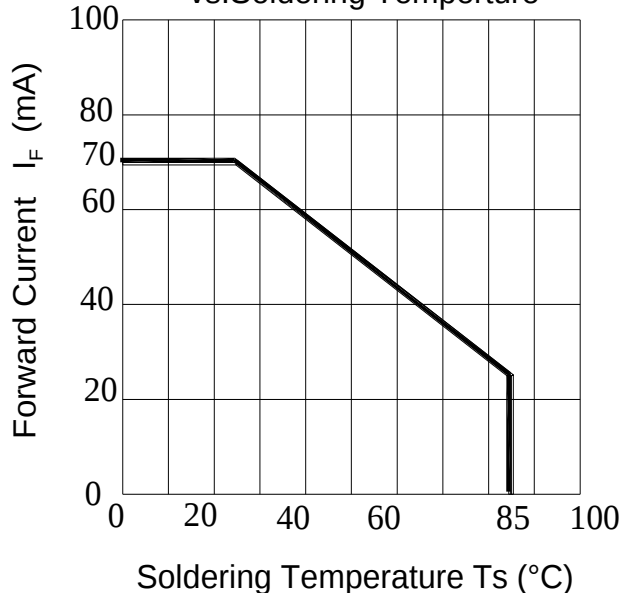
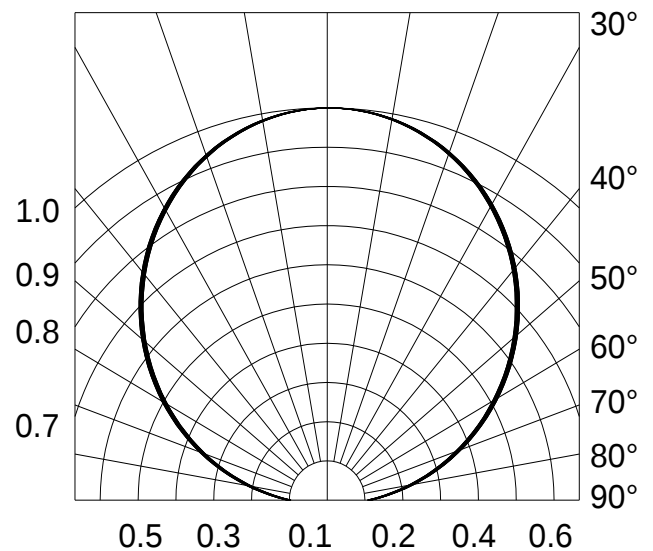
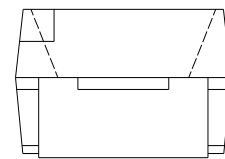
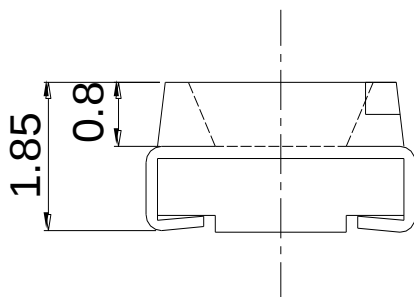
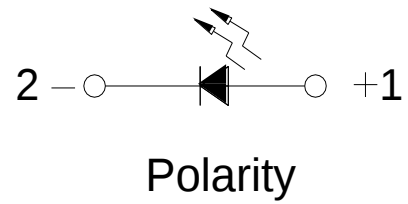
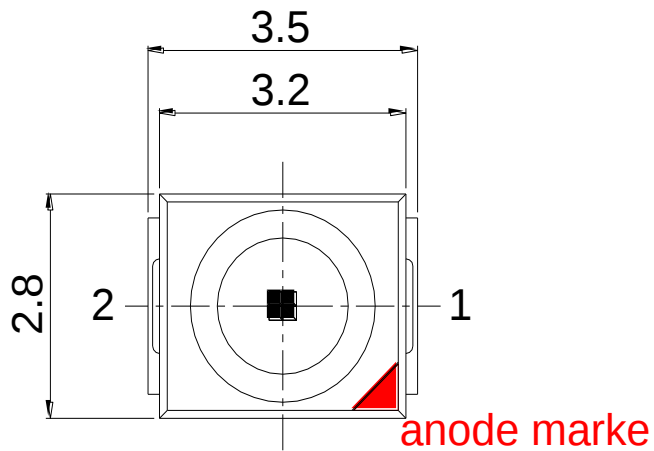


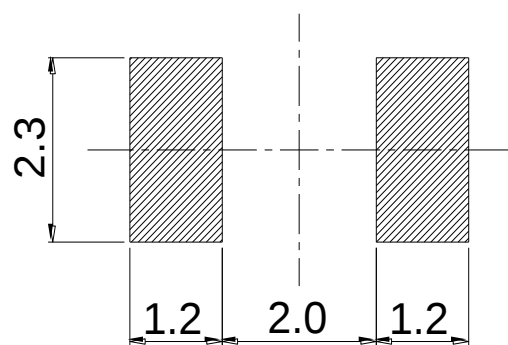
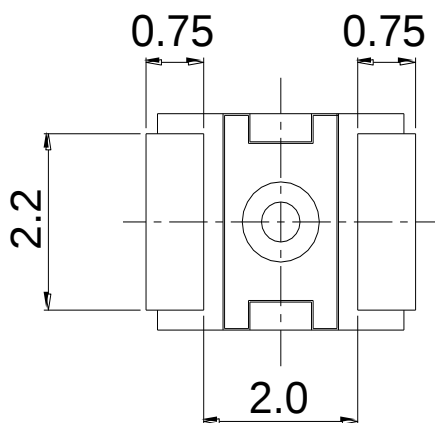
Fig.6-Radiation Diagram $T_a=25^{\circ}\text{C}$



Package Dimension



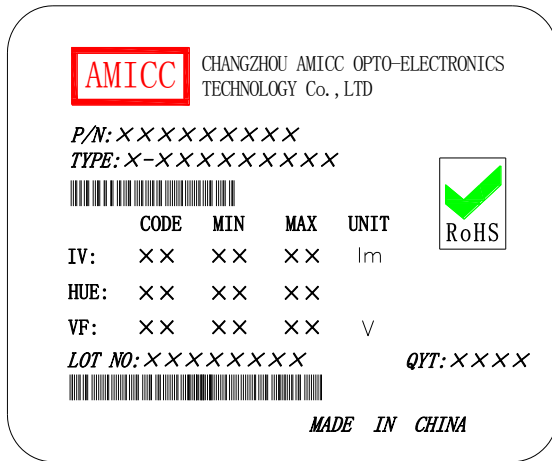
Recommended solder pad



Note:
Tolerance unless mentioned is ± 0.1 mm, Unit = mm

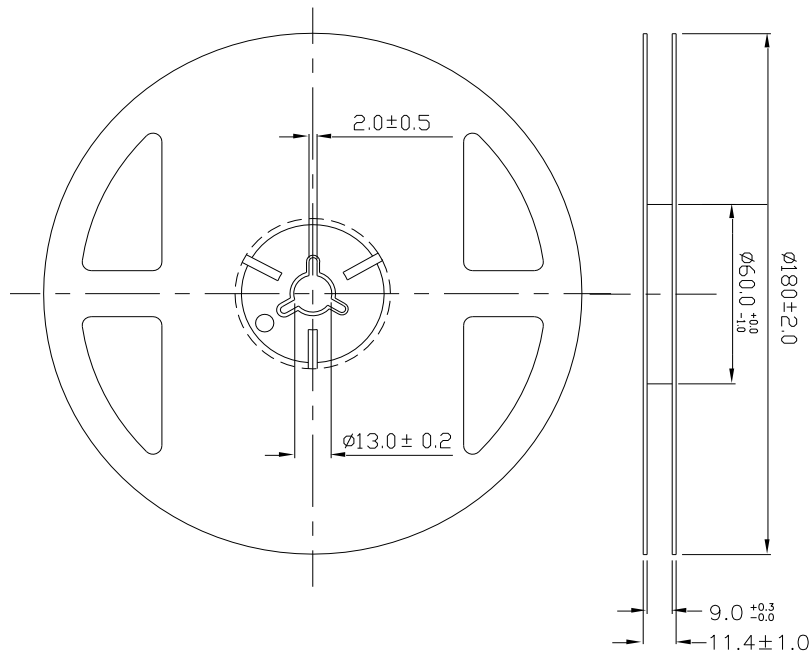
Moisture Resistant Packing Materials

Label Explanation



- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

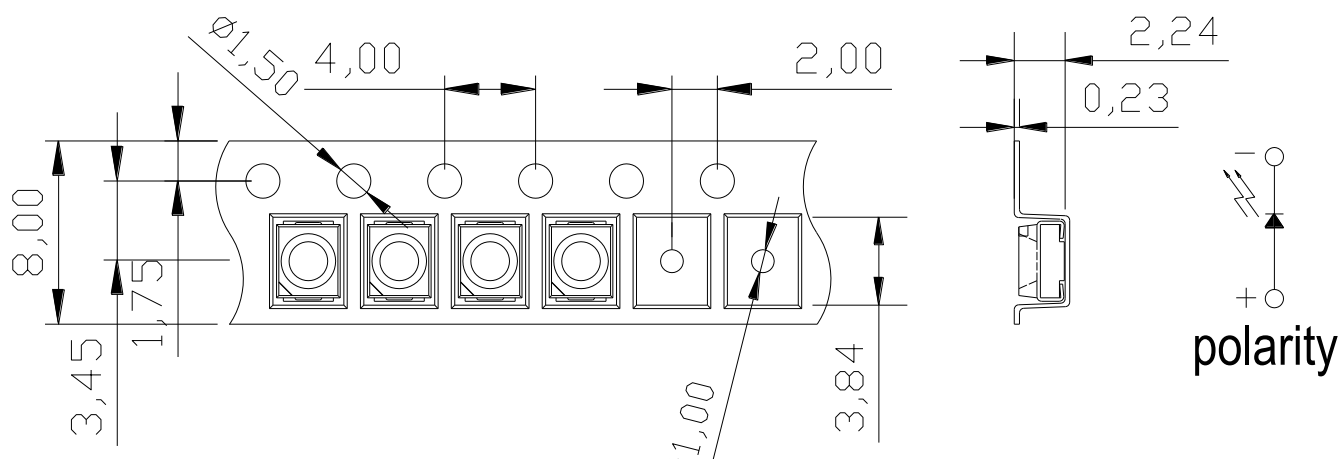
Reel Dimensions



Note:

Tolerances unless mentioned $\pm 0.1\text{mm}$, Unit = mm

Progressive direction



1.Tolerance unless mentioned is $\pm 0.1\text{mm}$,Unit = mm
2.Minimum packing amount is 1000 pcs per reel.

The diagram illustrates the packaging process for the sensor module in three stages:

- Initial Assembly:** A circular sensor module with a central chip and four corner components is shown. A label is placed on the central chip.
- Bagging:** The sensor module is placed inside an aluminum moisture-proof bag. A desiccant packet is added to the bag. The bag is then sealed.
- Boxing:** The sealed moisture-proof bag is placed inside a larger cardboard box. A label is placed on the outside of the box.

Reliability Test Items and Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

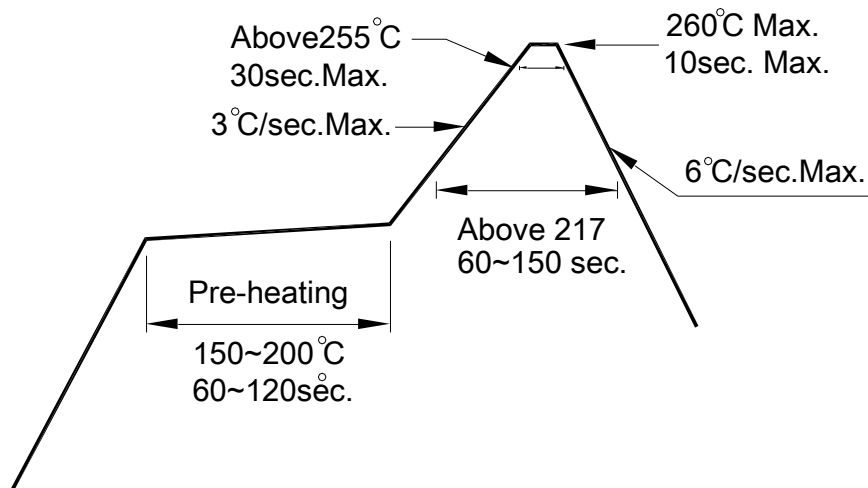
LTPD : 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C/10sec.	6 Min.	22 PCS.	0/1
2	Thermal Shock	H : +100°C 5min ┆ 10 sec L : -10°C 5min	300 Cycles	22 PCS.	0/1
3	Temperature Cycle	H : +100°C 15min ┆ 5 min L : -40°C 15min	300 Cycles	22 PCS.	0/1
4	High Temperature/Humidity Reverse Bias	Ta=85°C,85%RH	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Ta=-40°C	1000 Hrs.	22 PCS.	0/1
6	High Temperature Storage	Ta=100°C	1000 Hrs.	22 PCS.	0/1
7	DC Operation Life	Ta=25°C I _F = 40 mA	1000 Hrs.	22 PCS.	0/1

Precautions for Use

1. Over-current-proof
Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).
2. Storage
 - 2.1 Do not open moisture proof bag before the products are ready to use.
 - 2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.
 - 2.3 After opening the package: The LED's floor life is 168 Hrs under 30°C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
 - 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.
Baking treatment: 60±5°C for 24 hours.

3. Soldering Condition
 - 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
 - 3.3 When soldering, do not put stress on the LEDs during heating.
 - 3.4 After soldering, do not warp the circuit board.
4. Soldering Iron
Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.
5. Repairing
Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.